

SURFACE MOUNT RECTIFIERS

REVERSE VOLTAGE: 50 --- 1000 V
CURRENT: 3.0 A

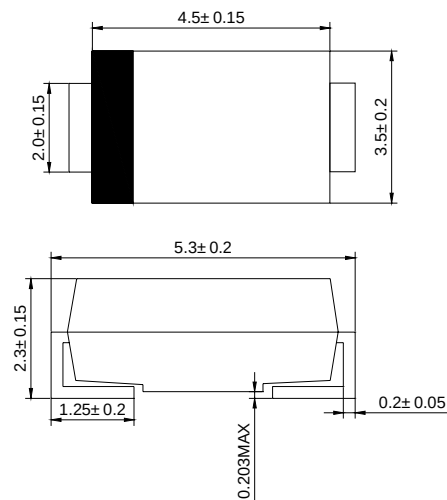
FEATURES

- ◇ Plastic package has underwriters laborator flammability classification 94V-0
- ◇ For surface mounted applications
- ◇ Low profile package
- ◇ Built-in strain relief, ideal for automated placement
- ◇ Glass passivated chip junction
- ◇ High temperature soldering:
250°C/10 seconds at terminals

MECHANICAL DATA

- ◇ Case: JEDEC DO-214AA, molded plastic over passivated chip
- ◇ Terminals: Solder plated, solderable per ML-STD-750, Method 2026
- ◇ Polarity: color band denotes cathode end
- ◇ Weight: 0.003 ounces, 0.093 gram

DO - 214AA(SMB)



Dimensions in millimeters

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified

		RS3AB	RS3BB	RS3DB	RS3GB	RS3JB	RS3KB	RS3MB	UNITS
Maximum recurrent peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	100	V
Maximum average forward rectified current at $T_L=90^{\circ}\text{C}$	$I_{F(AV)}$	3.0							A
Peak forward surge current @ $T_L = 110^{\circ}\text{C}$ 8.3ms single half-sine-wave superimposed on rated load	I_{FSM}	100.0							A
Maximum instantaneous forward voltage at 3.0A	V_F	1.30							V
Maximum DC reverse current @ $T_A=25^{\circ}\text{C}$ at rated DC blockjing voltage @ $T_A=125^{\circ}\text{C}$	I_R	5.0 200.0							$\mu\text{ A}$
Maximum reverse recovery time (NOTE 1)	t_{rr}	150				250	500		ns
Typical junction capacitance (NOTE 2)	C_J	32							pF
Typical thermal resitance (NOTE 3)	$R_{\theta JA}$	40.0							$^{\circ}\text{C/W}$
Operating junction and storage temperature range	$T_J T_{STG}$	-55-----+150							$^{\circ}\text{C}$

NOTE: 1.Reverse recovery time test conditions: $I_F=0.5A$, $I_R=1.0A$, $t_{rr}=0.25A$

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2. Measured at 1.0MHz and applied reverse voltage of 4.0 Volts

3. Thermal resistance from junction to ambient and junction to lead P.C.B.mounted on 0.2"X0.2"(5.0X5.0mm²) copper pad areas

FIG.1 -- FORWARD DERATING CURVE

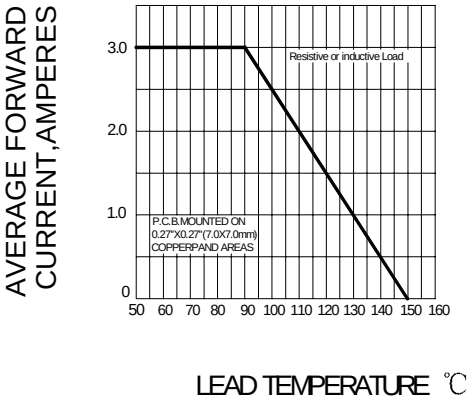


FIG.2 PEAK FORWARD SURGE CURRENT

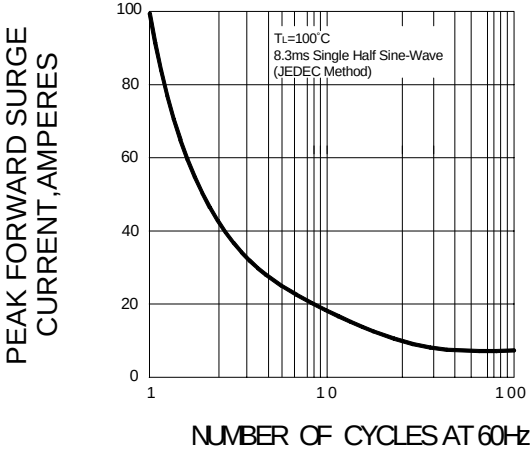


FIG.3 -- TYPICAL FORWARD CHARACTERISTICS

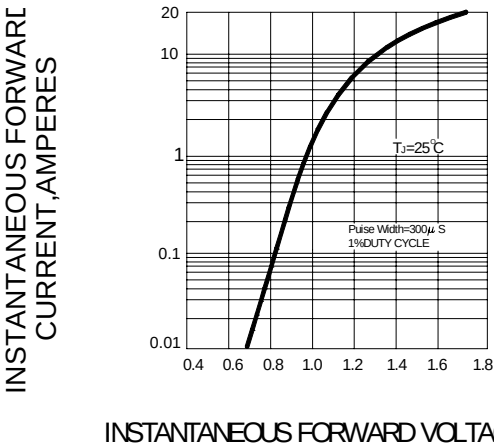


FIG.4 -- TYPICAL REVERSE CHARACTERISTICS

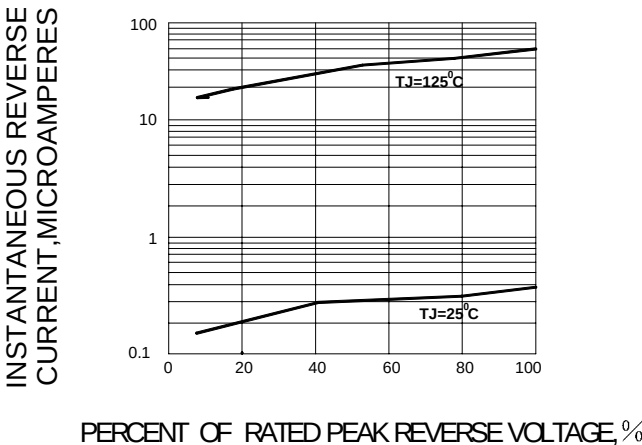


FIG.5-TYPICAL JUNCTION CAPACITANCE

